

REMARKS

This is a divisional application of patent application Serial Number 08/815,656. The title and the specification have been amended. Claims 1-10 have been cancelled. Claims 11-19 remain and these claims are presented for examination.

Respectfully submitted,

RATNER & PRESTIA

Daniel N. Calder
Daniel N. Calder, Reg. No. 27,424

Attorney for Applicants

DNC/pb

Attachment: Version with Markings to Show Changes Made

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Suite 301
One Westlakes, Berwyn
P.O. Box 980
Valley Forge, PA 19482-0980
(610) 407-0700

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Kathleen Libby
Kathleen Libby

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE TITLE:

[PROCESS TO PRODUCE A HIGH TEMPERATURE
INTERCONNECTION] LOW TEMPERATURE SOLDER CHIP ATTACH
STRUCTURE.

IN THE SPECIFICATION:

Insert before the first line of the specification --This application is a divisional of U.S. Patent Application Serial Number 08/815,656, filed on March 13, 1997, which has been allowed.--

IN THE CLAIMS:

Claims 1-10 have been cancelled.

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